

IN THE CLAIMS

Current Listing Of Claims:

1. (Currently Amended) A method comprising:
~~providing a thermally conductive heat spreader body having a first surface configured to thermally couple the heat spreader to an IC die; and~~
coating the first surface with an organic surface protectant
coating a thermally conductive heat spreader body with an organic surface protectant;
and
coupling the heat spreader body directly to a thermal interface material, the thermal interface material in direct contact with an IC die.
2. (original) A method as claimed in claim 1, wherein the coating step comprises immersing the heat spreader body in a dipping solution comprising the organic surface protectant.
3. (original) A method as claimed in claim 1, wherein the organic surface protectant comprises one or more triazole compounds and/or salts thereof.
4. (Cancelled)
5. (Currently Amended) A method as claimed in claim ~~[[4]]~~ 1, wherein the thermal interface material is a solder or solder-polymer hybrid.
6. (original) A method as claimed in claim 1, wherein the first surface of the heat spreader body is coated with an intervening layer before coating with an organic surface protectant.

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7. (Currently Amended) A method as claimed in claim 1, wherein the heat spreader body comprises copper.

8-23. (cancelled)